

## United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/707,687	01/05/2004	Kai-Chi Chen	11843-US-PA	1686
31561 7	7590 08/10/2005		EXAMINER	
JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE 7 FLOOR-1, NO. 100			LEWIS, MONICA	
	ROAD, SECTION 2		ART UNIT	PAPER NUMBER
TAIPEI, 100			2822	
TAIWAN			DATE MAILED: 08/10/2009	ξ

Please find below and/or attached an Office communication concerning this application or proceeding.

			- 1
	Application No.	Applicant(s)	
	10/707,687	CHEN ET AL.	
Office Action Summary	Examiner	Art Unit	
	Monica Lewis	. 2822	
The MAILING DATE of this communication Period for Reply	n appears on the cover sheet v	vith the correspondence address	
A SHORTENED STATUTORY PERIOD FOR F THE MAILING DATE OF THIS COMMUNICAT  - Extensions of time may be available under the provisions of 37 C after SIX (6) MONTHS from the mailing date of this communicati  - If the period for reply specified above is less than thirty (30) days  - If NO period for reply is specified above, the maximum statutory  - Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ION.  FR 1.136(a). In no event, however, may a on.  , a reply within the statutory minimum of th period will apply and will expire SIX (6) MO statute, cause the application to become A	reply be timely filed  rty (30) days will be considered timely.  NTHS from the mailing date of this communication.  BANDONED (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on	05 January 2004.		
<u> </u>	This action is non-final.		
3) Since this application is in condition for a closed in accordance with the practice ur	llowance except for formal ma		
Disposition of Claims			
4) ☐ Claim(s) 1-26 is/are pending in the application 4a) Of the above claim(s) is/are with 5) ☐ Claim(s) is/are allowed.  6) ☐ Claim(s) is/are rejected.  7) ☐ Claim(s) is/are objected to.  8) ☐ Claim(s) 1-26 are subject to restriction are	thdrawn from consideration.		
Application Papers			
9) The specification is objected to by the Exa	aminer.		
10)☐ The drawing(s) filed on is/are: a)☐	accepted or b) objected to	by the Examiner.	
Applicant may not request that any objection to	to the drawing(s) be held in abeya	ince. See 37 CFR 1.85(a).	
Replacement drawing sheet(s) including the call to be call to be the call to be call to be the c	•	•	
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for for a) All b) Some * c) None of:  1. Certified copies of the priority docu 2. Certified copies of the priority docu 3. Copies of the certified copies of the application from the International B * See the attached detailed Office action for	ments have been received. Iments have been received in e priority documents have bee Bureau (PCT Rule 17.2(a)).	Application No n received in this National Stage	
Attachment(s)	□	O (DTO 442)	
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-94)</li> </ol>	• —	Summary (PTO-413) (s)/Mail Date	
Information Disclosure Statement(s) (PTO-1449 or PTO/5 Paper No(s)/Mail Date	· · · · · · · · · · · · · · · · · · ·	Informal Patent Application (PTO-152)	

## **DETAILED ACTION**

1. This action is in response to the application filed January 5, 2004.

## Election/Restrictions

- 2. Restriction to one of the following inventions is required under 35 U.S.C. 121:
  - I. Claim 1-20, drawn to a semiconductor device with a chip package structure, classified in class 257, subclass 678.
  - II. Claims 21-26, drawn to the method of fabricating a semiconductor device with chip package structure, classified in class 438, subclass 106.

Inventions II and I are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make other and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). The product can be made by the following methods: a) the heat sink could be attached to the chip by an electrically insulating layer or a flexible epoxy adhesive instead of using a thermal conductive layer.

Because these inventions are distinct for the reasons given above and have acquired a separate status in the art as shown by their different classification, restriction for examination purposes as indicated is proper.

Applicant is reminded that upon the cancellation of claims to a non-elected invention, the inventorship must be amended in compliance with 37 CFR 1.48(b) if one or more of the currently named inventors is no longer an inventor of at least one claim remaining in the application. Any amendment of inventorship must be accompanied by a request under 37 CFR 1.48(b) and by the fee required under 37 CFR 1.17(i).

Applicant is advised that the reply to this requirement to be complete must include an election of the invention to be examined even though the requirement be traversed (37 CFR 1.143).

3. If the Applicant selects Invention I disclosed then application contains claims directed to the following patentably distinct species of the claimed invention:

Embodiment I (Claims 1-8), directed to a semiconductor device comprising a carrier, a chip having an active surface with a plurality of bumps, wherein the chip is flipped and bonded to the carrier, a heat sink set over the chip and an encapsulating material layer, filling a bonding gap between the chip and carrier and covering the carrier;

Embodiment II (Claims 9-13 and claims 16-20), directed to a semiconductor device comprising a carrier, a chipset which comprises a first chip having a first active surface, wherein the first chip is attached to the carrier such that the first active surface is positioned away from the carrier and a second chip having a second active surface with a plurality of bumps thereon, wherein the chipset comprises a plurality of chips, at least one chip is bonded to the carrier, a heat sink set over the chipset, an encapsulating layer filling the flip-chip bonding gap and covering the carrier; and

Embodiment III (Claims 9-11 and 14-20), directed to a semiconductor device comprising a carrier, a chipset which comprises a first chip having a first active surface with a plurality of bumps thereon, wherein the first active surface of the first chip is bonded and electrically connected to the carrier and a second chip

Application/Control Number: 10/707,687 Page 4

Art Unit: 2822

having a second active surface wherein the second chip is attached to the first chip such that the second active surface is positioned away from the first chip, and a third chip having a third active surface with a plurality of second bumps thereon, a heat sink set over the chipset, an encapsulating layer filling the flip-chip bonding gap and covering the carrier.

Applicant is required under 35 U.S.C. 121 to elect a single disclosed species for prosecution on the merits to which the claims shall be restricted if no generic claim is finally held to be allowable. Currently, none are generic.

Applicant is advised that a reply to this requirement must include an identification of the species that is elected consonant with this requirement, and a listing of all claims readable thereon, including any claims subsequently added. An argument that a claim is allowable or that all claims are generic is considered nonresponsive unless accompanied by an election.

Upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which are written in dependent form or otherwise include all the limitations of an allowed generic claim as provided by 37 CFR 1.141. If claims are added after the election, applicant must indicate which are readable upon the elected species. MPEP § 809.02(a).

## Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica Lewis whose telephone number is 571-272-1838.

Application/Control Number: 10/707,687

Art Unit: 2822

Page 5

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-308-7722 for regular and after final communications. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML

August 8, 2005

MM 2800